

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2568801

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ching-Wen Hung</td> <td>09/05/2013</td> </tr> <tr> <td>Jia-Rong Wu</td> <td>09/05/2013</td> </tr> <tr> <td>Chih-Sen Huang</td> <td>09/05/2013</td> </tr> <tr> <td>Chieh-Te Chen</td> <td>09/05/2013</td> </tr> </tbody> </table>		Name	Execution Date	Ching-Wen Hung	09/05/2013	Jia-Rong Wu	09/05/2013	Chih-Sen Huang	09/05/2013	Chieh-Te Chen	09/05/2013
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Jia-Rong Wu	09/05/2013										
Chih-Sen Huang	09/05/2013										
Chieh-Te Chen	09/05/2013										
RECEIVING PARTY DATA											
Name:	UNITED MICROELECTRONICS CORP.										
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park										
City:	Hsin-Chu City										
State/Country:	TAIWAN										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14048043</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14048043						
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Application Number:	14048043										
CORRESPONDENCE DATA											
Fax Number:	(703)997-4517										
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Email:	Patent.admin.uspto.cr@naipo.com										
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>											
Correspondent Name:	WINSTON HSU										
Address Line 1:	P.O.BOX 506										
Address Line 4:	MERRIFIELD, VIRGINIA 22116										
ATTORNEY DOCKET NUMBER:	NAUP1989USA										
NAME OF SUBMITTER:	SHELLEY KUO										
Signature:	/SHELLEY KUO/										
Date:	10/08/2013										

PATENT

Total Attachments: 8

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:
METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WINTNESS WHEREOF, I have hereunto set hand and seal this SEP 05 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP1989USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ching-Wen Hung

Date: SEP 05 2013

Signature: Ching-Wen Hung

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Jia-Rong Wu**

Date: **SEP 05 2013**

Signature: Jia-Rong Wu

NPO#NAU-P1989-USA:0
CUST#UMCD-2013-0182

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DSC0-102U008784

PATENT
REEL: 031359 FRAME: 0117

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Inventor: Chih-Sen Huang

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Signature: Chih-Sen Huang

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Signature: Chieh-Te Chen

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RECORDED: 10/08/2013

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